

SOT2228-2(D)

HQFN28, thermal enhanced quad flat package, no leads, 0.1 dimple wettable flank, 28 terminals, 0.8 mm pitch, 8 mm x 6 mm x 1.9 mm body

15 February 2024

Package information



1 Package summary

Terminal position code	Q (quad)
Package type descriptive code	HQFN28
Package style descriptive code	HQFN (thermal enhanced quad flatpack; no leads)
Package body material type	P (plastic)
Mounting method type	S (surface mount)
Issue date	18-12-2023
Manufacturer package code	98ASA02185D

Table 1. Package summary

Parameter	Min	Nom	Max	Unit
package length	7.9	8	8.1	mm
package width	5.9	6	6.1	mm
seated height	1.85	1.9	1.95	mm
nominal pitch	-	0.8	-	mm
actual quantity of termination	-	28	-	



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2 Package outline

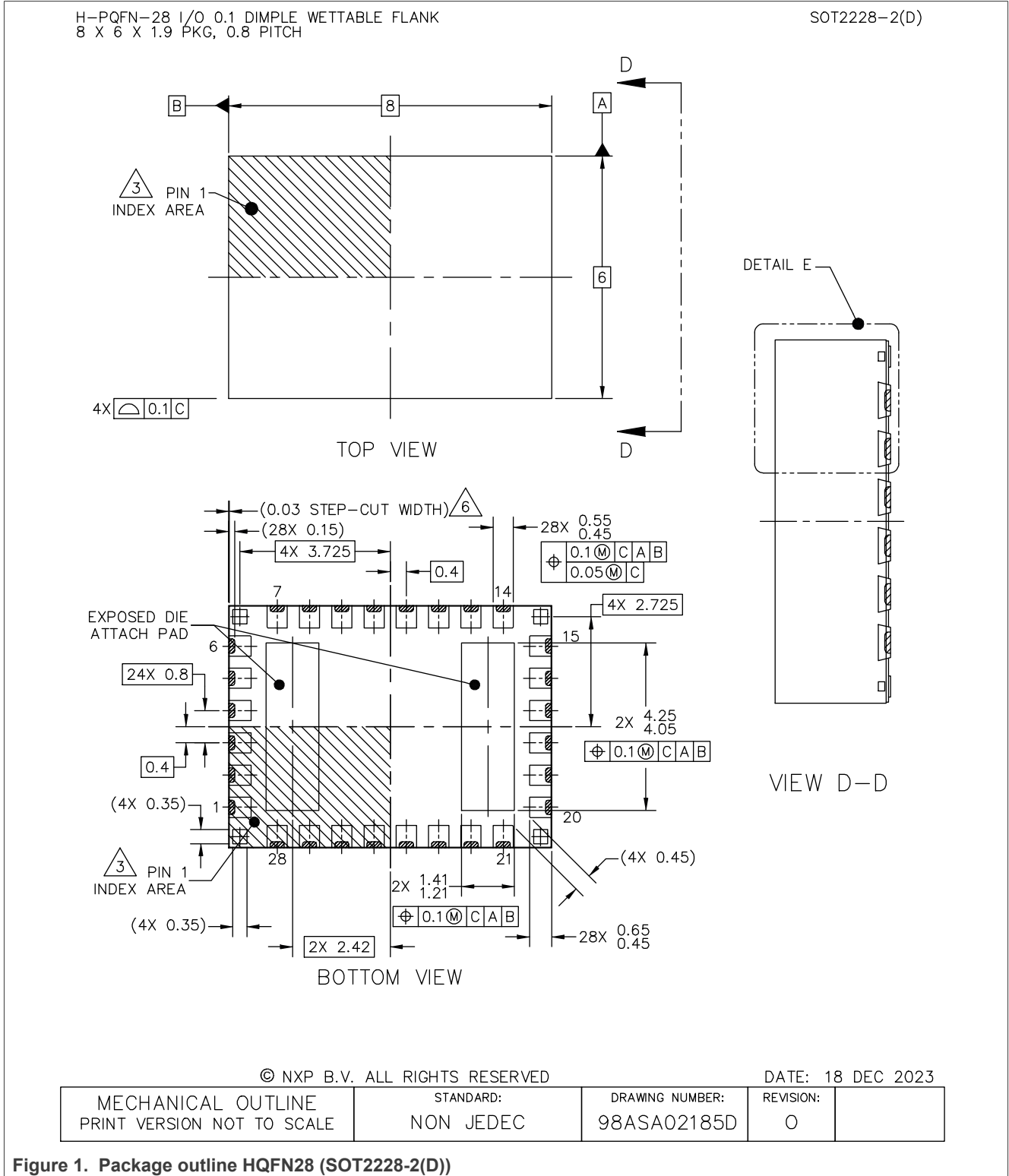
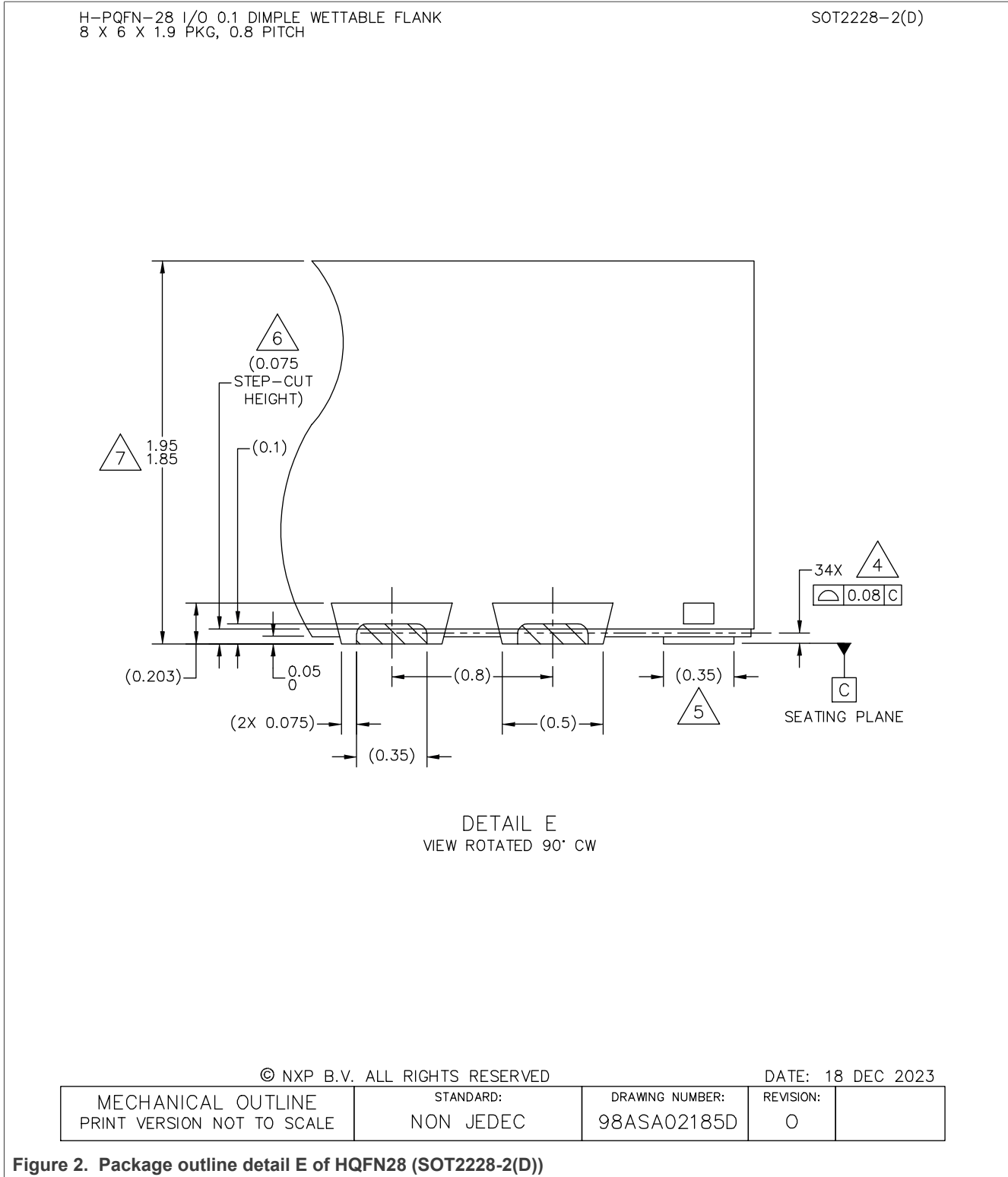


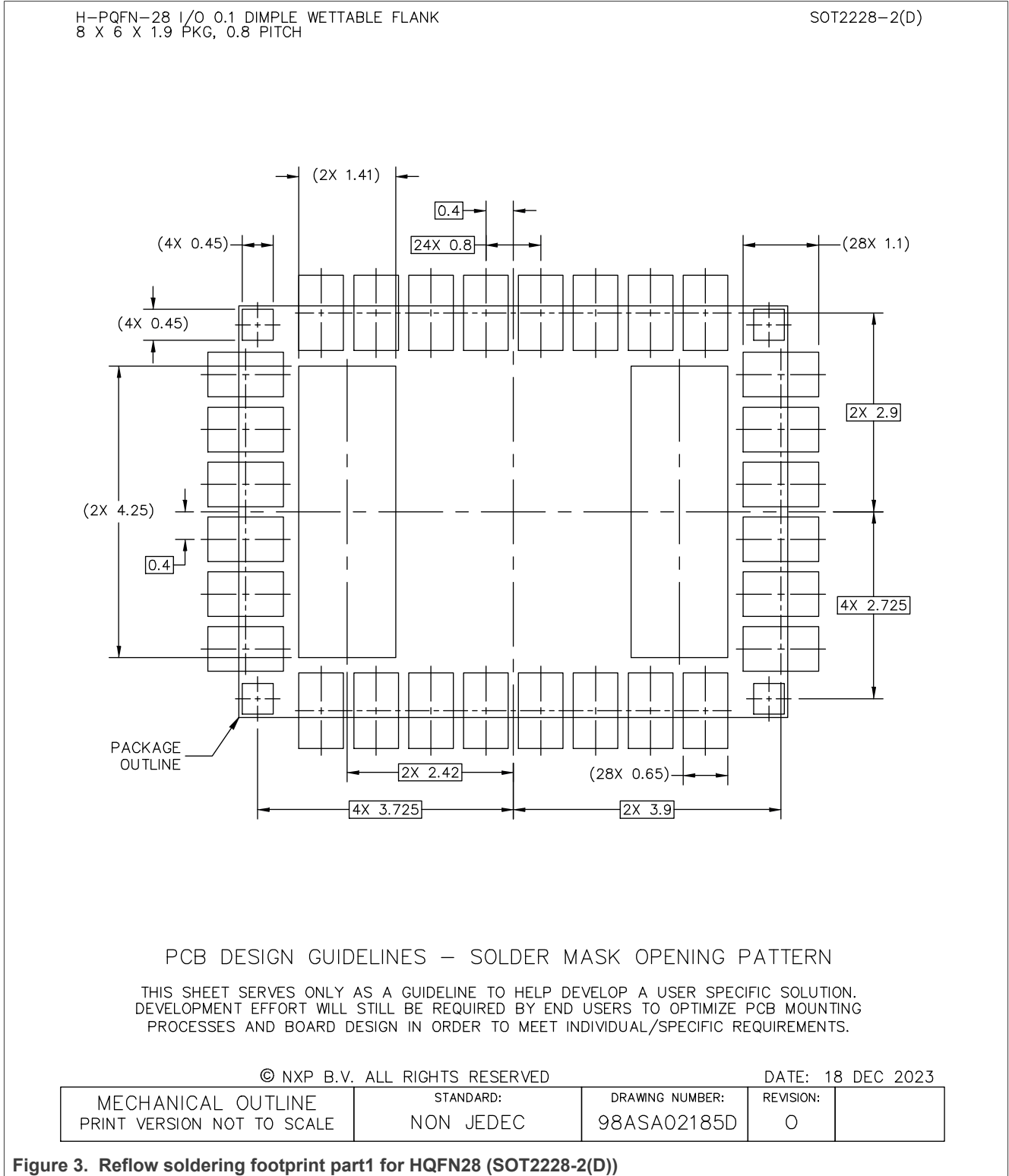
Figure 1. Package outline HQFN28 (SOT2228-2(D))

HQFN28, thermal enhanced quad flat package, no leads, 0.1 dimple wettable flank, 28 terminals, 0.8 mm pitch, 8 mm x 6 mm x 1.9 mm body

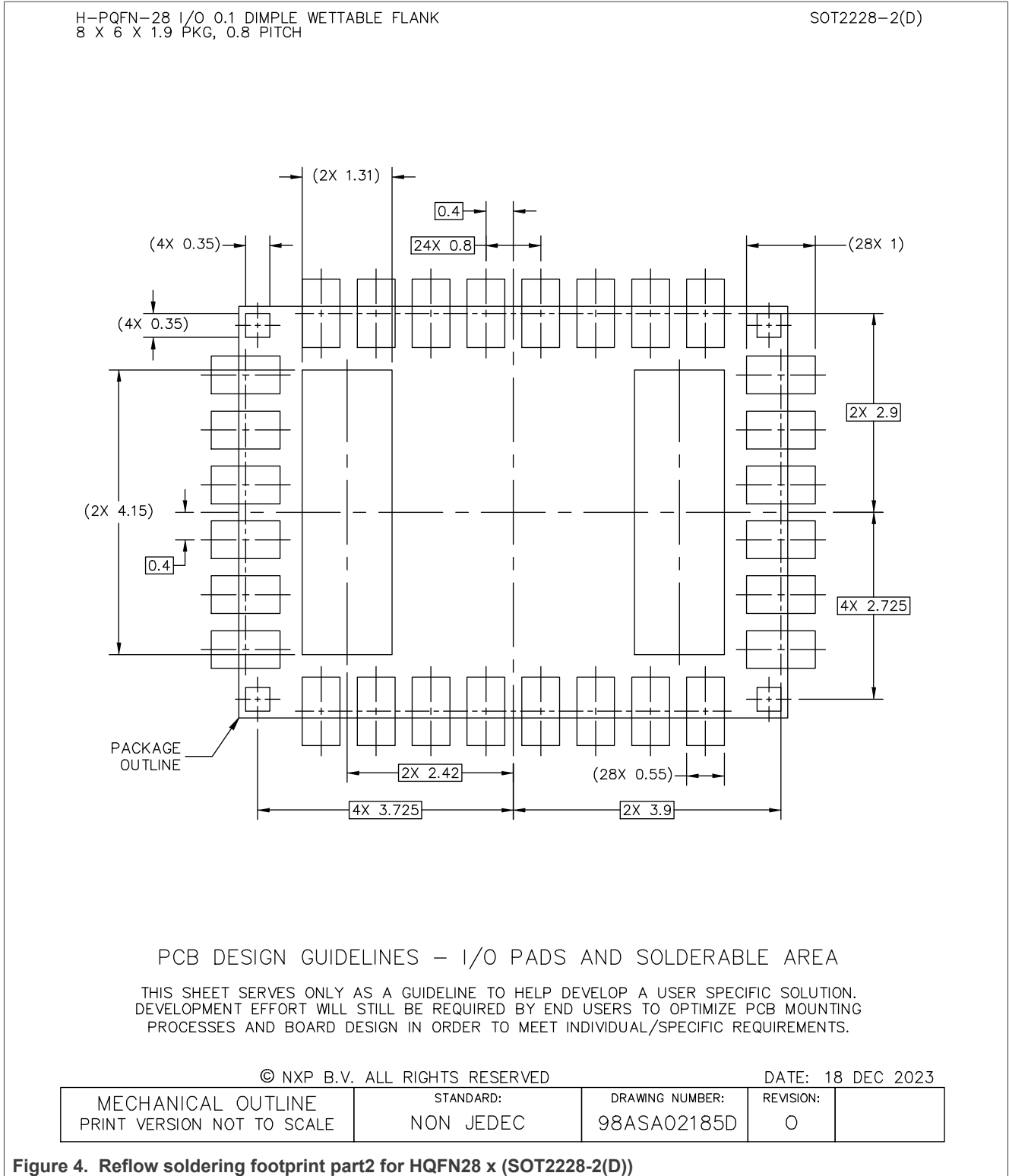


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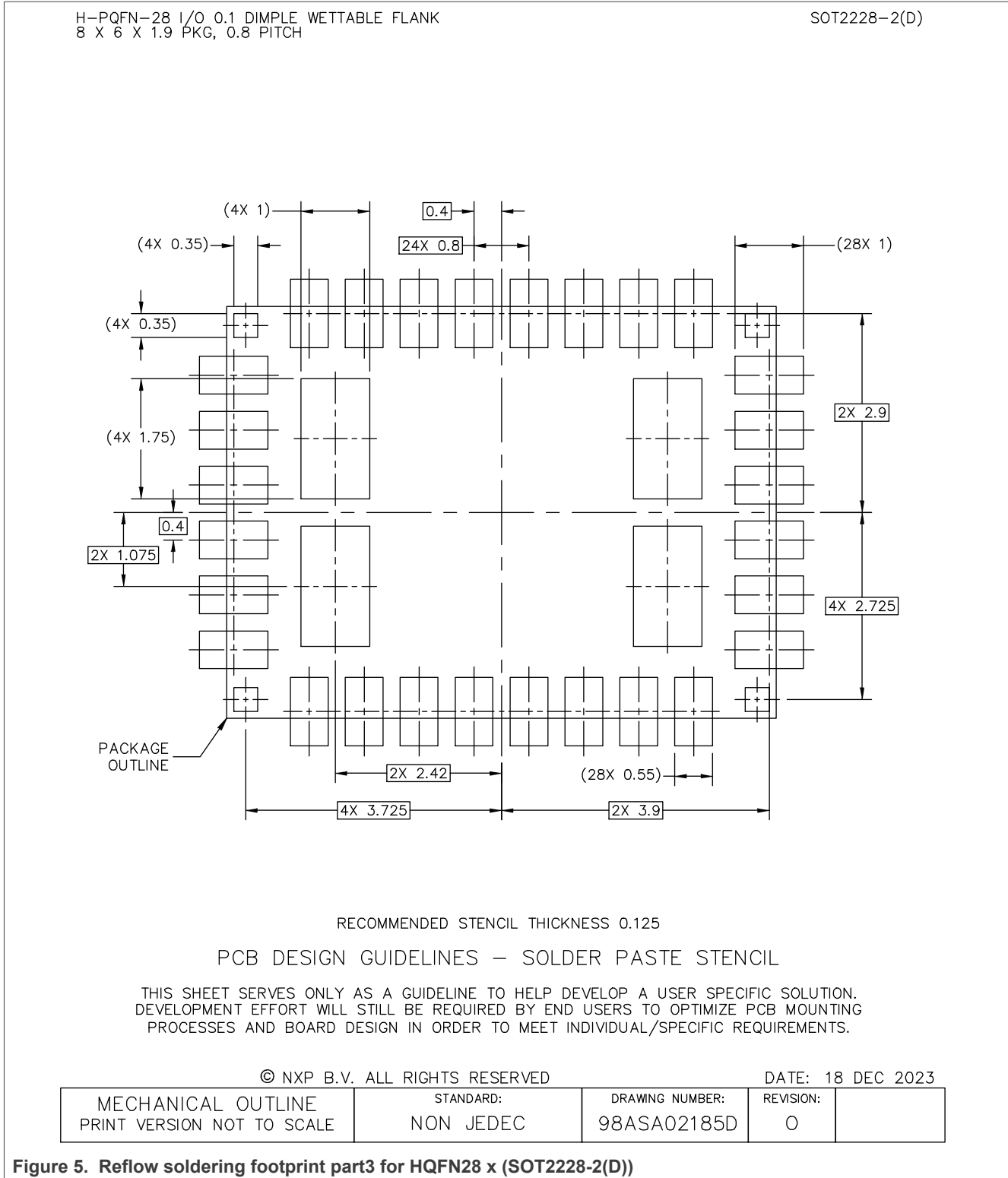
3 Soldering



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H-PQFN-28 I/O 0.1 DIMPLE WETTABLE FLANK
8 X 6 X 1.9 PKG, 0.8 PITCH

SOT2228-2(D)

NOTES:

1. ALL DIMENSIONS ARE IN MILLIMETERS.
2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.
3. PIN 1 FEATURE SHAPE, SIZE AND LOCATION MAY VARY.
4. COPLANARITY APPLIES TO LEADS, DIE ATTACH FLAG AND CORNER NON-FUNCTIONAL PADS.
5. ANCHORING PADS.
6. STEP-CUT IS APPLIED FOR BURR REMOVAL ONLY.
7. SPUTTER LAYER OF STAINLESS STEEL SUS316 IS INCLUDED IN THE TOP SIDE SURFACE.

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DATE: 18 DEC 2023

MECHANICAL OUTLINE PRINT VERSION NOT TO SCALE	STANDARD: NON JEDEC	DRAWING NUMBER: 98ASA02185D	REVISION: 0
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Figure 6. Package outline note HQFN28 (SOT2228-2(D))

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4 Legal information

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Contents

1 Package summary1
2 Package outline2
3 Soldering4
4 Legal information8